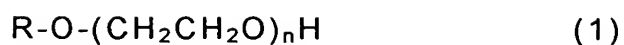


WHAT IS CLAIMED IS:

1. A liquid composition for cleaning a hydrophobic substrate which is used for cleaning a substrate having a surface area on which a water droplet exhibits a contact angle of 60° or more, comprising
5 of 60° or more, comprising
a phosphonic acid chelating agent having at least two phosphonic groups in one molecule and a polyoxyalkylene alkyl ether type of nonionic surfactant,
wherein a droplet of the liquid composition or a
10 dilute aqueous solution thereof exhibits a contact angle of 50° or less to the surface area.
2. The liquid composition for cleaning a hydrophobic substrate as claimed in Claim 1 wherein the surface area is a
15 low dielectric-constant film having a dielectric-constant of 4 or less.
3. The liquid composition for cleaning a hydrophobic substrate as claimed in Claim 1 wherein a droplet of an
20 aqueous solution prepared by dissolving the nonionic surfactant in water exhibits a contact angle of 50° or less to the surface area.
4. The liquid composition for cleaning a hydrophobic
25 substrate as claimed in Claim 1 wherein the nonionic surfactant is represented by general formula (1):



wherein R represents alkyl group having 8 to 22 carbon atoms and n represents an integer of 1 to 30.

5 5. The liquid composition for cleaning a hydrophobic substrate as claimed in Claim 1 wherein the phosphonic acid chelating agent is one or two or more selected from the group consisting of 1-hydroxyethylidene-1,1-diphosphonic acid, ethylenediamine tetramethylenephosphonic acid,
10 aminotrimethylenephosphonic acid and their salts.

 6. The liquid composition for cleaning a hydrophobic substrate as claimed in Claim 1 wherein pH is within the range of 2 to 6.

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 7. A process for cleaning a substrate having a surface area where a water droplet exhibits a contact angle of 60° or more, comprising the steps of preparing the liquid composition as claimed in Claim 1 and removing adherent materials on the
20 substrate surface while feeding the liquid composition or a dilute aqueous solution thereof to the substrate surface.

 8. The cleaning process as claimed in Claim 7 wherein the substrate surface is scrubbed with a brush while feeding the
25 liquid composition or a dilute aqueous solution thereof to the substrate surface.

9. The cleaning process as claimed in Claim 7 wherein the adhesive materials to be removed are particles and metallic contaminants.

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